

JCS55 U.S. PTO
10/020638
12/14/01

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10020638	FILING DATE 12/14/2001	CLASS 257	SUBCLASS 143	GAU 2811	EXAMINER 1527 Mitchell
**APPLICANTS: Ma Bodan; Hong Sun; Tong Quinn;					
**CONTINUING DATA VERIFIED:					
**FOREIGN APPLICATIONS VERIFIED:					
PG-PUB DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO 1979.EEM	
Verified and Acknowledged Examiners's initials					
TITLE : Dual cure B-stageable underfill for wafer level					
U.S. DEPT. OF COMMERCE PAT & TM-PTO-436 (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig. <input checked="" type="checkbox"/>	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

FILED WITH:

☐ DISK (CRF)

☐ CD-ROM

(Attached in pocket on right inside flap)